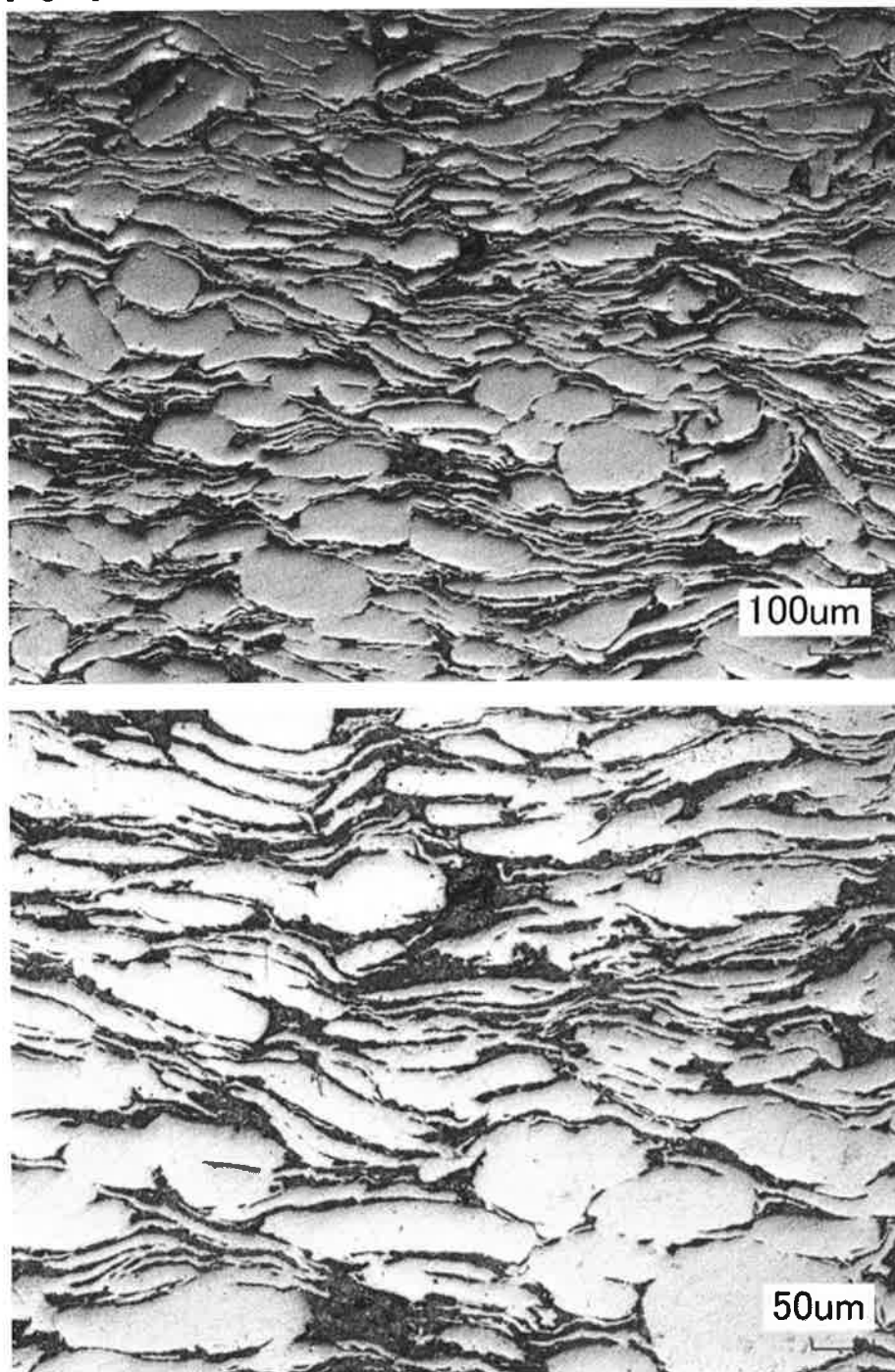


[Fig. 1]



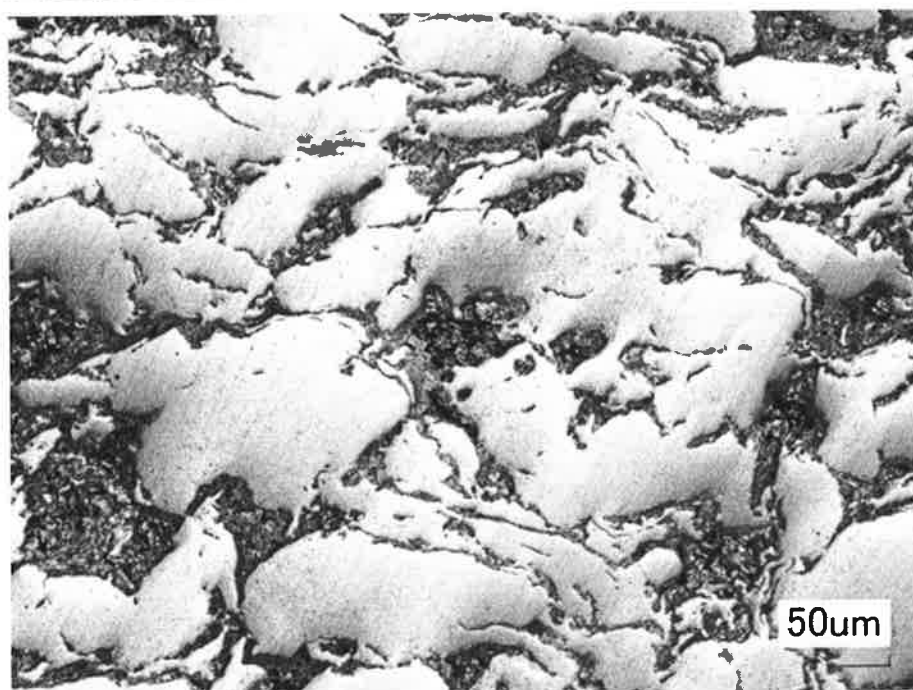
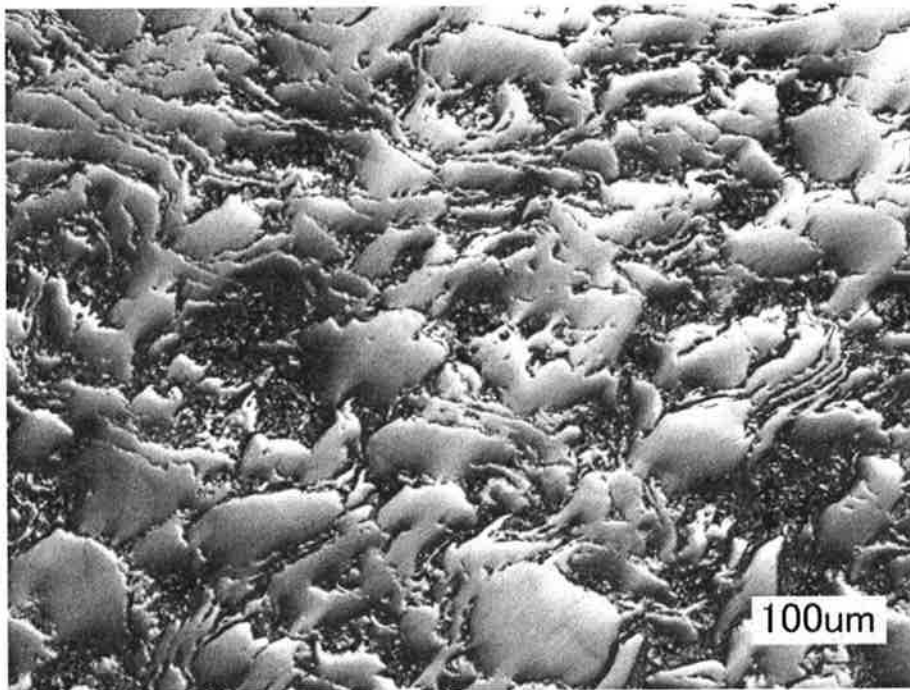
Example 1

Pulverized powder of Fe-Pt chips was used

Before flattening: 200 to 300 µm

Average grain size after flattening: 85 µm

[Fig. 2]

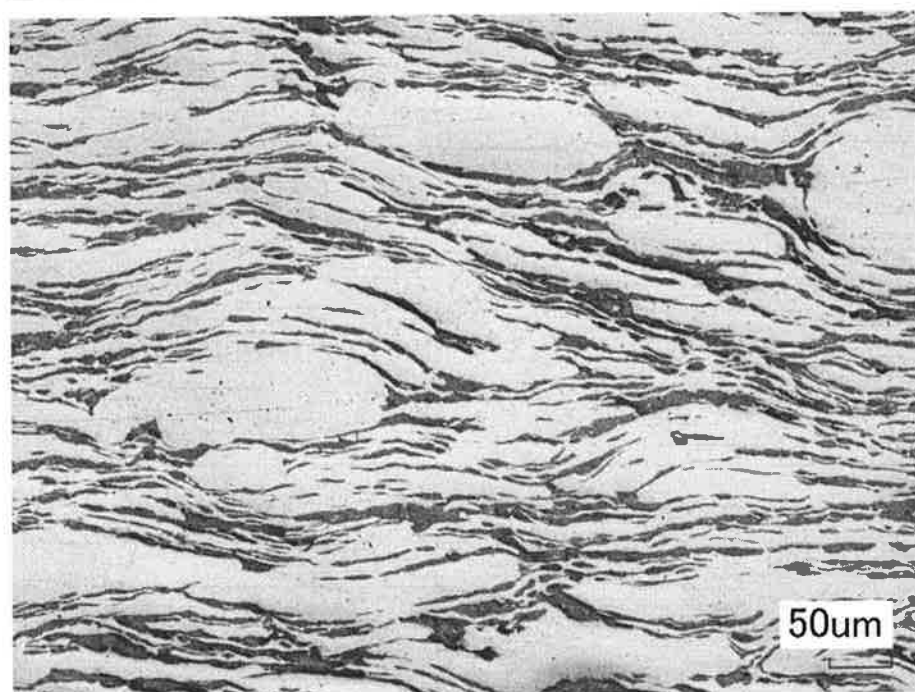
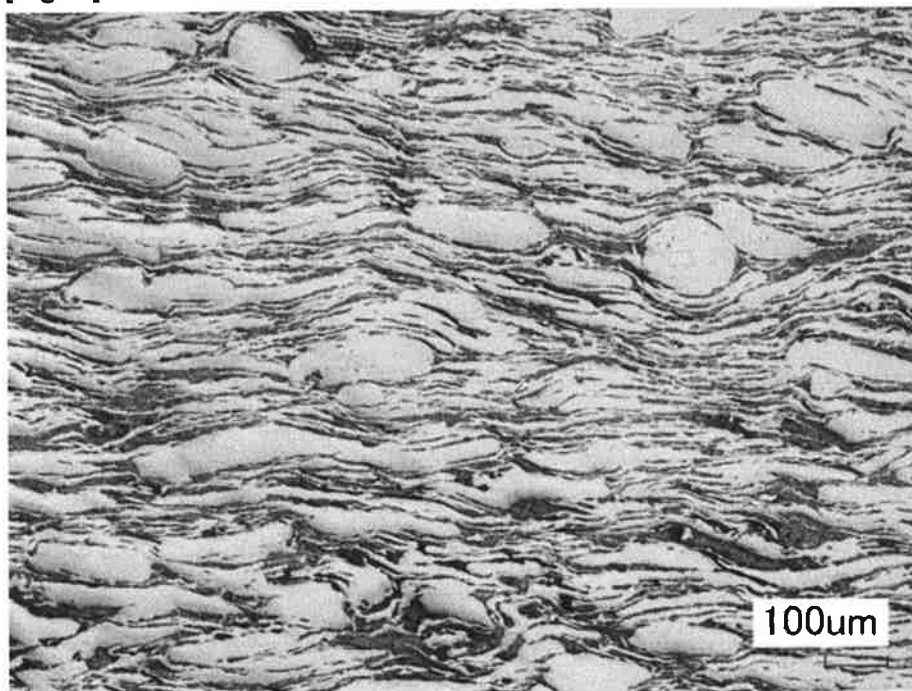
**Example 1**

Pulverized powder of Fe-Pt chips was used

Before flattening: 200 to 300 μm

Average grain size after flattening: 85 μm

[Fig. 3]



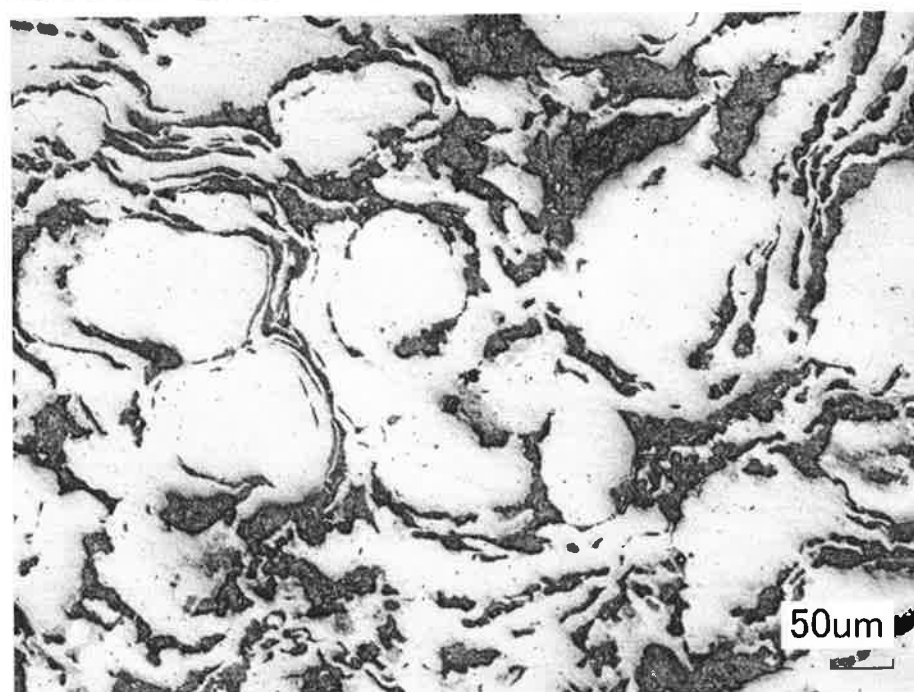
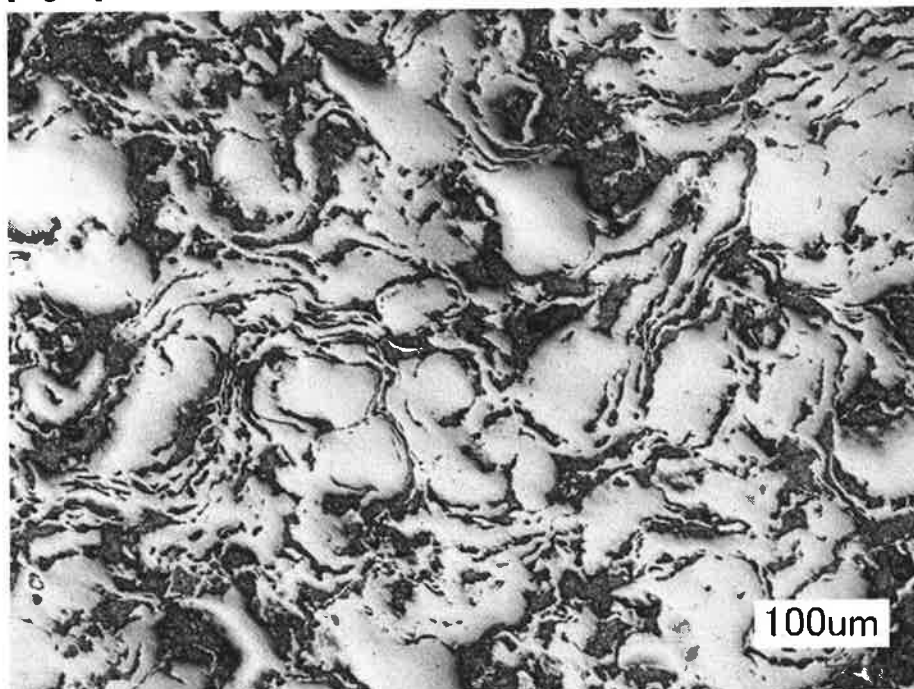
Example 2

Pulverized powder of Fe-Pt chips was used

Before flattening: 100 to 150 μm

Average grain size after flattening: 80 μm

[Fig. 4]



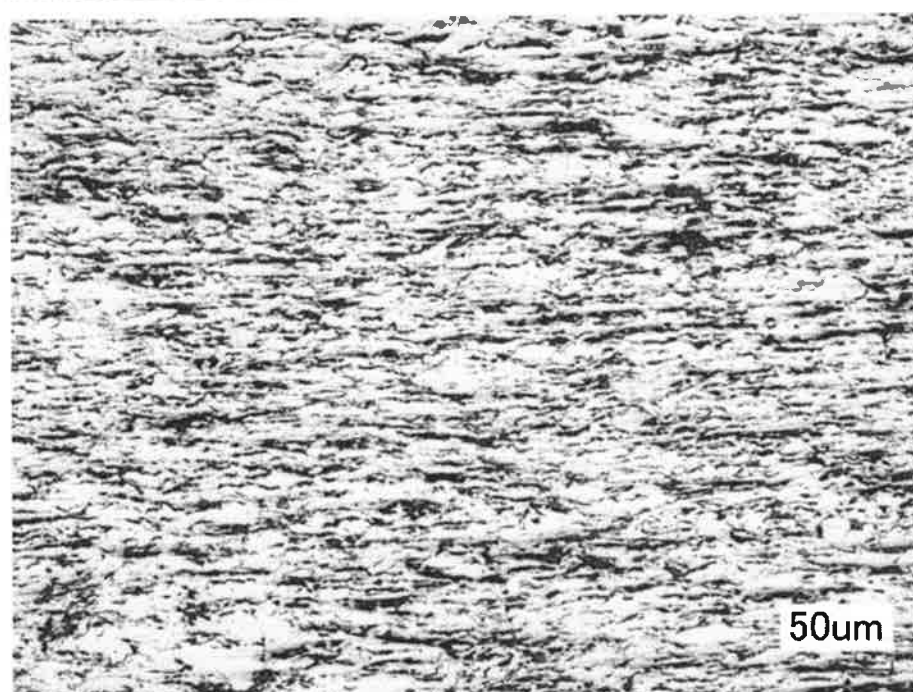
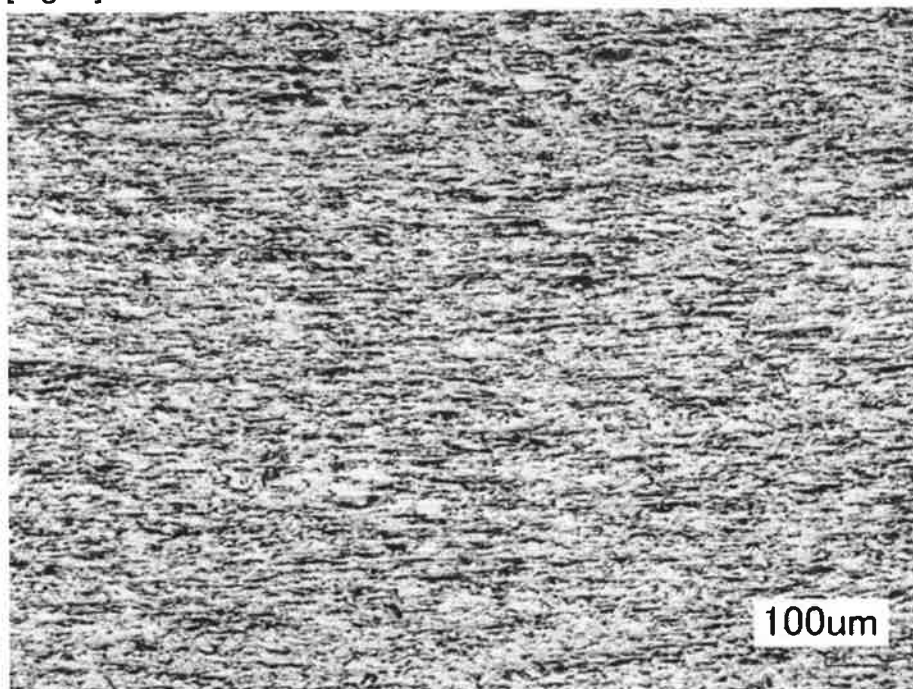
Example 2

Pulverized powder of Fe-Pt chips was used

Before flattening: 100 to 150 μm

Average grain size after flattening: 80 μm

[Fig. 5]

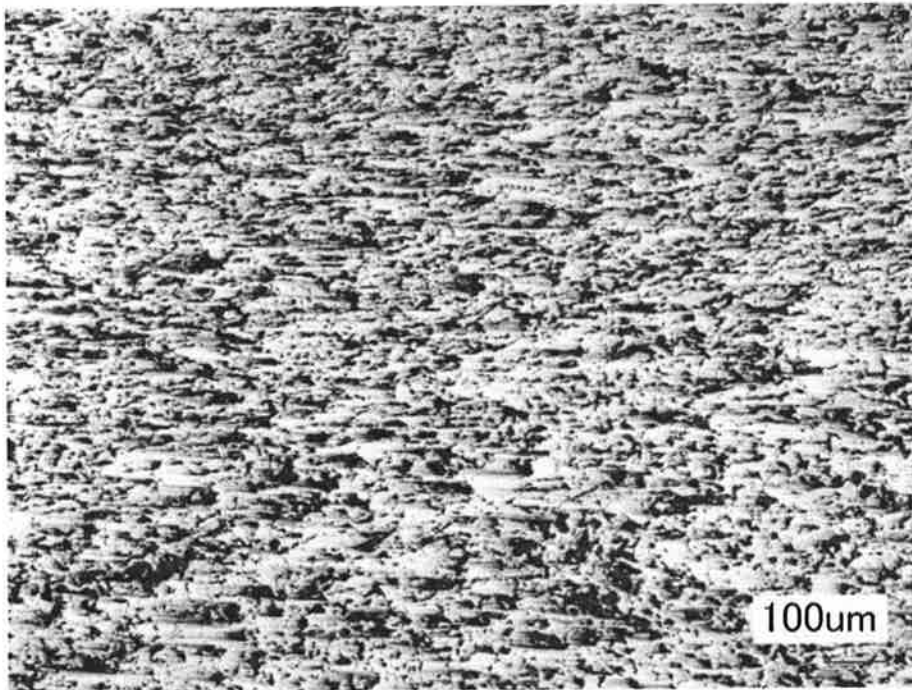


Comparative Example 1

Porous Fe-Pt powder was used

Average grain size after flattening: 11 μm

[Fig. 6]

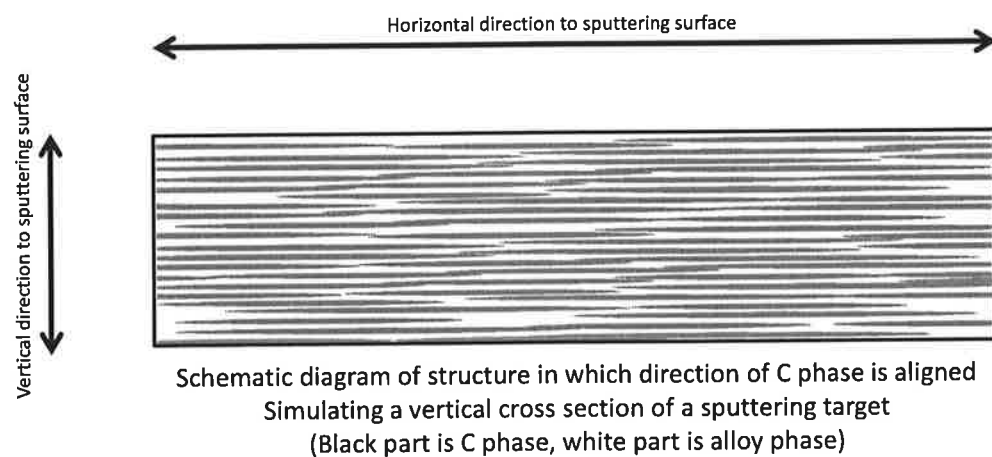


Comparative Example 1

Porous Fe-Pt powder was used

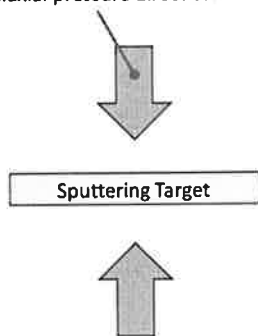
Average grain size after flattening: 11 μm

[Fig. 7]



[Fig. 8]

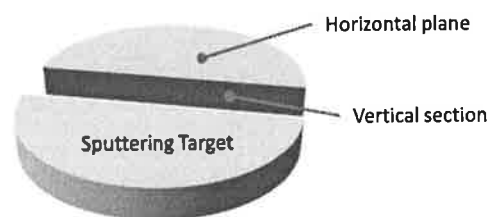
Uniaxial pressure direction



Schematic diagram of
sputtering target when
viewed edge-on



Schematic diagram of
sputtering target viewed from
directly above



Horizontal plane and vertical section